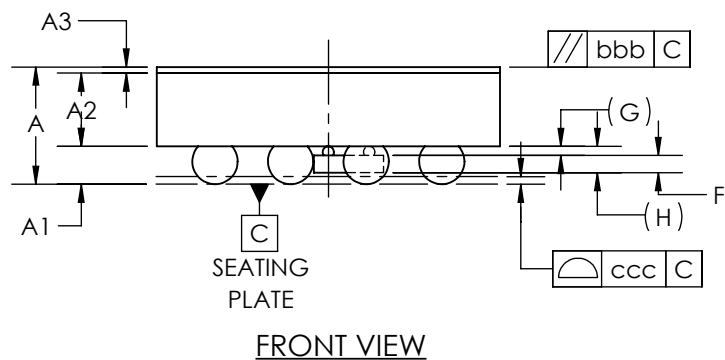
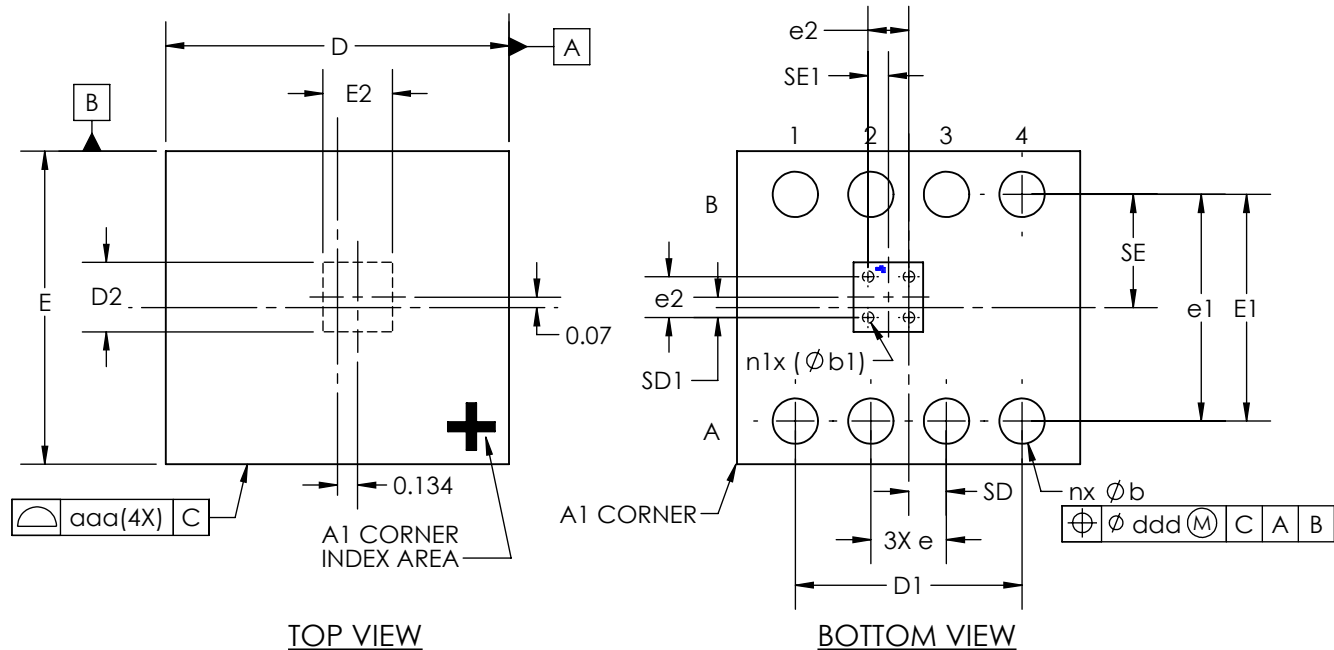




	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	0.717	0.775	0.833
	H	0.174	REF.	
STAND OFF	A1	0.22	---	0.28
	G	0.06	REF.	
WAFER THICKNESS	A2	0.475	0.5	0.525
	F	0.101	0.114	0.127
FILM THICKNESS	A3	0.022	0.025	0.028
BODY SIZE	X D	2.27		
	Y E	2.07		
	X E2	0.46		
	Y D2	0.46		
BALL/BUMP PITCH	X SD	0.25	BSC	
	Y SE	0.75	BSC	
	X SE1	0.135	BSC	
	Y SD1	0.135	BSC	
EDGE BALL CENTER TO CENTER	X D1	1.5	BSC	
	Y E1	1.5	BSC	
PITCH	e	0.5	BSC	
	e1	1.5	BSC	
	e2	0.27	BSC	
BALL DIAMETER (SIZE)		0.3		
BALL/BUMP WIDTH	b	0.28	---	0.34
	b1	0.075	REF.	
BALL/BUMP COUNT	n	8		
	n1	4		
PACKAGE EDGE TOLERANCE	aaa	0.03		
WAFER FLATNESS	bbb	0.06		
COPLANARITY	ccc	0.05		
BALL/BUMP OFFSET (PACKAGE)	ddd	0.015		

- DRAWING NOT TO SCALE -



TITLE PACKAGE OUTLINE 8 BUMPS
WLP PKG. CUSTOM PITCH, K82A2+1

APPROVAL	DOCUMENT CONTROL NO.	REV.	1/1
	21-100336	B	